

L Number	Hits	Search Text	DB	Time stamp
-	151534	438.clas.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 10:52
-	464469	((bond\$4 or attach\$4 or connect\$4) with (substrate or wafer or die))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 10:53
-	35962	438.clas. and (((bond\$4 or attach\$4 or connect\$4) with (substrate or wafer or die)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 10:53
-	32015	(438.clas. and (((bond\$4 or attach\$4 or connect\$4) with (substrate or wafer or die)))) and (connect\$5 or interconnect\$5 or electrical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 11:29
-	29	((438.clas. and (((bond\$4 or attach\$4 or connect\$4) with (substrate or wafer or die)))) and (connect\$5 or interconnect\$5 or electrical)) and (first adj contact adj (element or structure))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 11:30
-	19	((438.clas. and (((bond\$4 or attach\$4 or connect\$4) with (substrate or wafer or die)))) and (connect\$5 or interconnect\$5 or electrical)) and (first adj contact adj (element or structure)) and (second adj contact adj (element or structure))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 11:31